Celanese
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Zytel® HTN51G45HSL BK083

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN51G45HSL BK083 is a 45% glass reinforced, heat stabilized, lubricated, hydrolysis resistant high performance polyamide resin. It is also a PPA resin.

Product information

Resin Identification	PA6T/XT-GF45	ISO 1043
Part Marking Code	>PA6T/XT-GF45<	ISO 11469
Part Marking Code	>PPA-GF45<	SAE J1344
ISO designation	ISO 16396-PA6T/XT,GF45,M1CGHR,S10-140	

Rheological properties

	dry/cond.		
Moulding shrinkage, parallel	0.1 / -	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.6 / -	%	ISO 294-4, 2577
Moulding shrinkage, parallel, annealed	0.2 / *	%	ISO 294-4
Moulding shrinkage, normal, annealed	0.7 / *	%	ISO 294-4

Typical mechanical properties

	dry/cond.		
Tensile modulus	16000 / 16000	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	260 / 250	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	2.3 / 2	%	ISO 527-1/-2
Flexural modulus	14000 / -	MPa	ISO 178
Flexural strength	370 / -	MPa	ISO 178
Charpy impact strength, 23°C	85 / 65	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	75 / 55[A]	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	12 / 11	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	12 / 10[A]	kJ/m²	ISO 179/1eA
Izod notched impact strength, 23°C	12 / -	kJ/m²	ISO 180/1A
Izod notched impact strength, -40°C	13.0 / -	kJ/m²	ISO 180/1A
Poisson's ratio	0.33 / 0.33		

[A]: Assessed

Thermal properties

	dry/cond.		
Melting temperature, 10°C/min	300 / *	°C	ISO 11357-1/-3
Melting temperature, first heat	300 / *	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	140 / 95	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	265 / *	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	285 / *	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel, -40-23°C	14 / *	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	14 / *	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, parallel, 55-160°C	15 / *	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal, -40-23°C	45 / *	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	50 / *	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal, 55-160°C	69 / *	E-6/K	ISO 11359-1/-2
RTI, electrical, 0.75mm	150	°C	UL 746B

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RTI, electrical, 1.5mm	150	°C	UL 746B
RTI, electrical, 3.0mm	150	°C	UL 746B
RTI, impact, 0.75mm	120	°C	UL 746B
RTI, impact, 1.5mm	125	°C	UL 746B
RTI, impact, 3.0mm	150	°C	UL 746B
RTI, strength, 0.75mm	130	°C	UL 746B
RTI, strength, 1.5mm	140 / *	°C	UL 746B
RTI, strength, 3.0mm	150	°C	UL 746B

Flammability

	dry/cond.		
Burning Behav. at 1.5mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	IEC 60695-11-10
UL recognition	yes / *		UL 94
Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.85 / *	mm	IEC 60695-11-10
UL recognition	yes / *		UL 94
FMVSS Class	SE		ISO 3795 (FMVSS 302)

Electrical properties

	dry/cond.		
Volume resistivity	>1E13 / -	Ohm.m	IEC 62631-3-1

Physical/Other properties

	dry/cond.		
Humidity absorption, 2mm	1.5 / *[C]	%	Sim. to ISO 62
Water absorption, 2mm	3.4 / *[C]	%	Sim. to ISO 62
Density	1570 / -	kg/m³	ISO 1183

[C]: Calculated

Injection

Drying Recommended	yes	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Melt Temperature Optimum	325	°C
Min. melt temperature	320	°C
Max. melt temperature	330	°C
Mold Temperature Optimum	150	°C
Min. mould temperature	140[1]	°C
Max. mould temperature	180	°C

[1]: Higher temperature needed for thinner sections.

Characteristics

Processing	Injection Moulding
Special characteristics	Heat stabilised or stable to heat, Hydrolysis resistant, Laser Markable

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Additional information

Injection molding	During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE. When lower mold temperatures are used, the initial warpage and shrinkage may be lower, but the surface appearance and chemical resistance may be reduced, and the dimensional change may be greater when parts are subsequently heated.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Bosch	N28 BN05-OX036	
General Motors	GMW16356P-PPA-GF45	Black
General Motors	GMW16360P-PPA-GF45	Black
Renault-Nissan	UB01b, No Spec, Special Part Approval, See Your CE Account Manager.	
Stellantis	B62 0300 / 61/213M/215E+/13/C1B	Technical Black
Stellantis	MS.50156 / PPA.GF45-50.14000T.12C.HS	CPN4749, 01994_10_00170
Stellantis - Chrysler	MS.50103 / CPN-4749	Black

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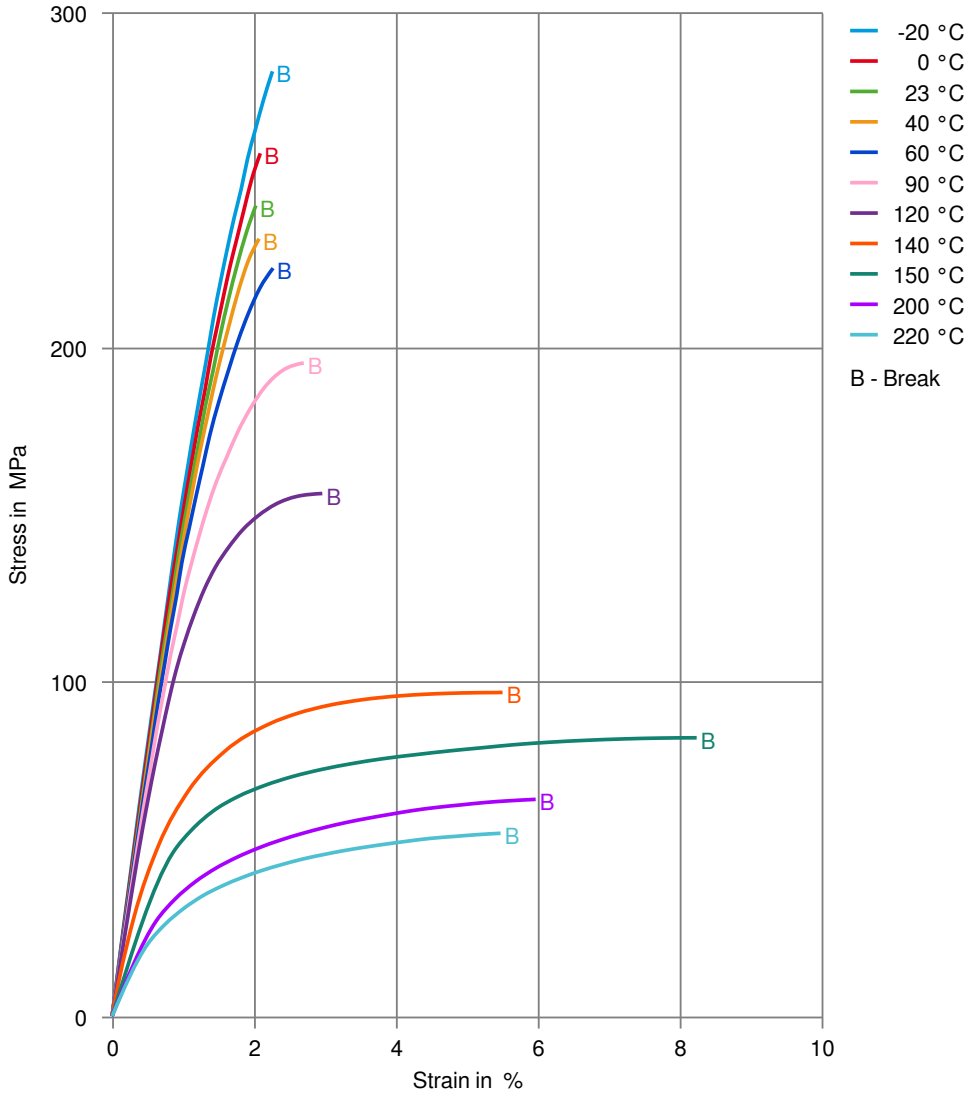
Stress-strain (dry)



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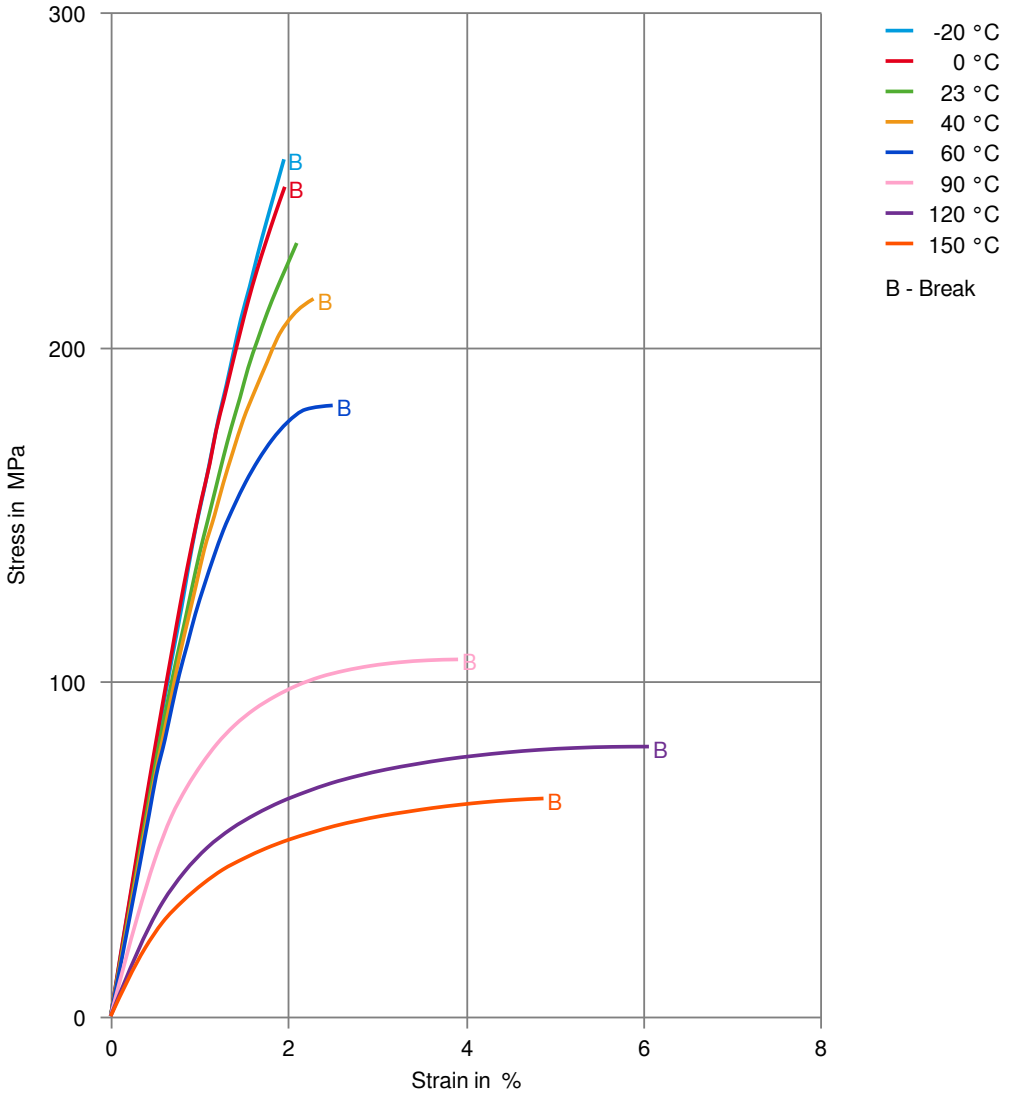
Stress-strain (cond.)



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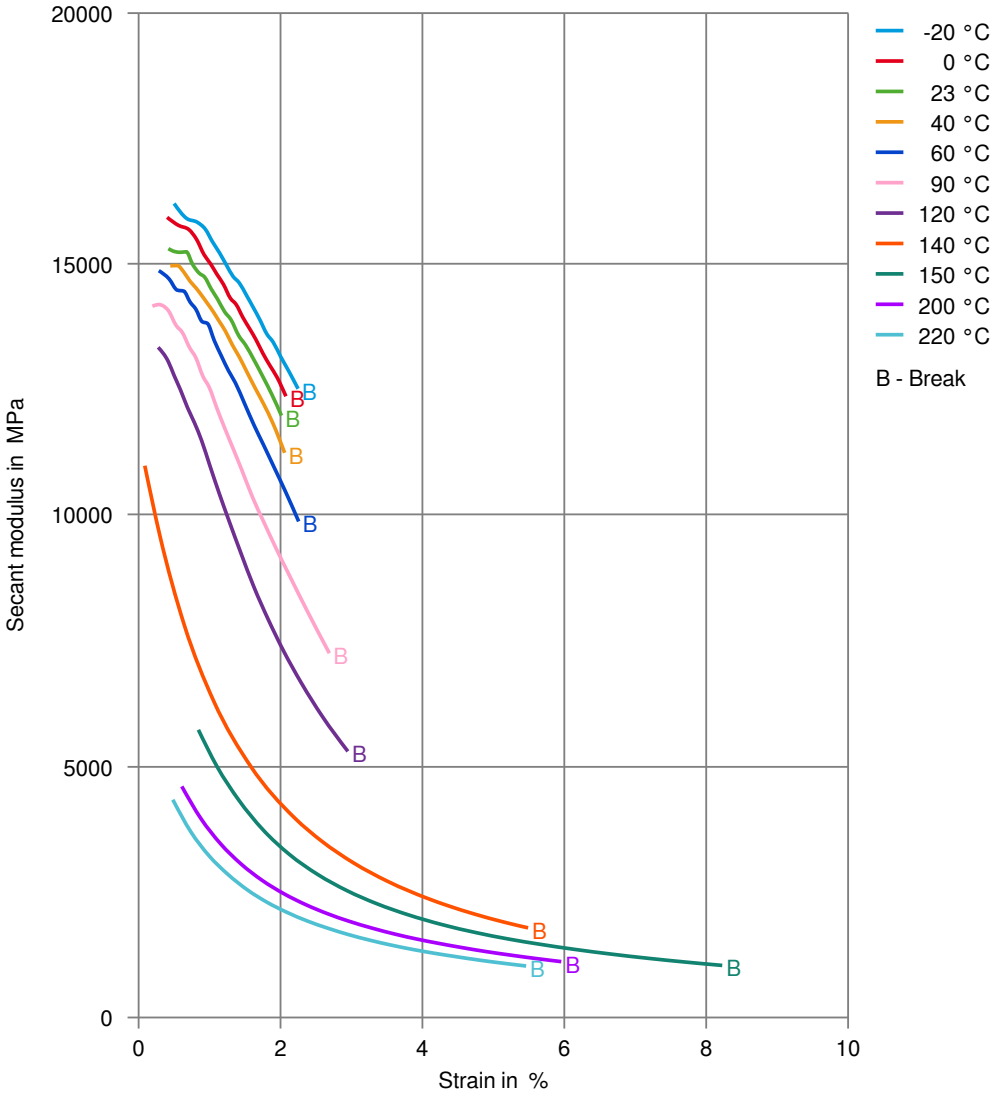
Secant modulus-strain (dry)



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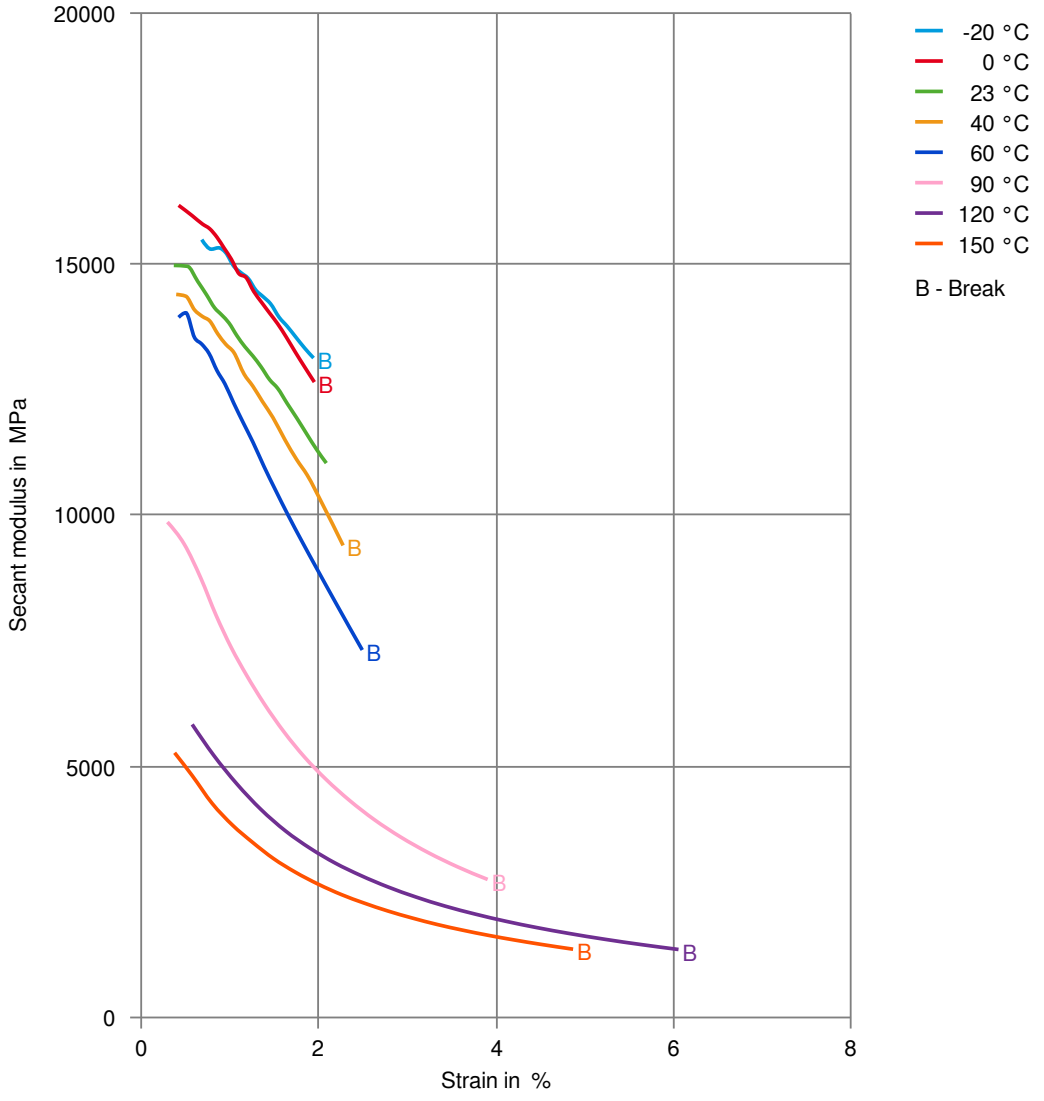
Secant modulus-strain (cond.)



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Chemical Media Resistance

Acids

- ✔ Acetic Acid (5% by mass), 23°C
- ✔ Citric Acid solution (10% by mass), 23°C
- ✔ Lactic Acid (10% by mass), 23°C

Other

- ✔ Ethylene Glycol (50% by mass) in water, 108°C
- ✔ Water, 23°C
- ✔ Water, 90°C
- ✔ Coolant Glysantin G48, 1:1 in water, 125°C

Symbols used:

✔ possibly resistant
Defined as: Supplier has sufficient indication that contact with chemical can be potentially accepted under the intended use conditions and expected service life. Criteria for assessment have to be indicated (e.g. surface aspect, volume change, property change).

✘ not recommended - see explanation
Defined as: Not recommended for general use. However, short-term exposure under certain restricted conditions could be acceptable (e.g. fast cleaning with thorough rinsing, spills, wiping, vapor exposure).

Revised: 2025-05-01 Source: Celanese Materials Database